

AZ P4903 – run sheet

Merck KGaA (AZ Electronic Materials)

[nanyte.com/photoresists/az-p4903](https://www.nanyte.com/photoresists/az-p4903) · last updated 2026-09-13

Thickness: 10–30 µm

Softbake: 95–115 °C

Exposure dose – dose by film thickness · Suss MA-200
mask aligner

Film thickness	Dose
1.5 µm	90 mJ/cm ²
3.5 µm	135 mJ/cm ²
12 µm	800 mJ/cm ²

Develop: Developer AZ 400K at 1:4, or at 1:3 / AZ 421K
(unbuffered) for films above 12 µm; AZ Developer 1:1 where
aluminium must not be etched; AZ 340 is also listed · Dilution
AZ 400K 1:4 for better selectivity on thinner films, 1:3 for
films above 12 µm; AZ Developer 1:1 · Method spray or immersion

Hardbake: 100–110 °C